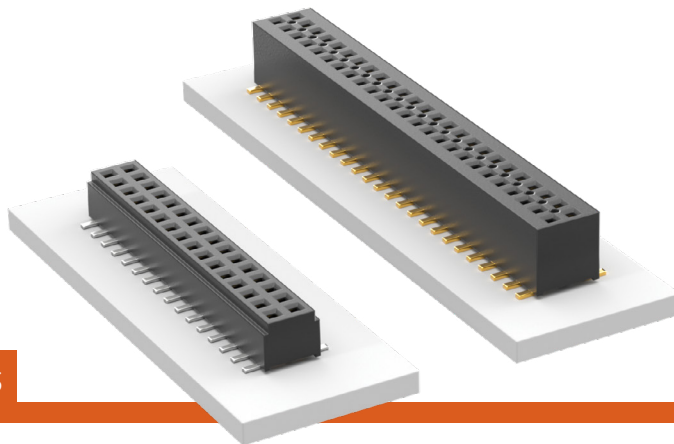


RUGGED RELIABLE MICRO SOCKETS

(1.00 mm) .0394" PITCH • CLM/MLE SERIES



CLM

Mates:

FTM, FTMH, MW

MLE

Mates:

FTM, FTMH, MW

SPECIFICATIONS

Insulator Material: Black LCP

Contact Material:

CLM: Phosphor Bronze

MLE: BeCu

Plating:

CLM: Au or Sn over

50 μ " (1.27 μ m) Ni

MLE: Au over 10 μ " (0.25 μ m) Ni

Operating Temp Range:

-55 °C to +125 °C

Current Rating (CLM/FTMH):

3.1 A per pin

(2 pins powered)

Current Rating (MLE/FTMH):

2.9 A per pin (2 pins powered)

Max Cycles:

CLM: 100 with 10 μ " (0.25 μ m) Au

Voltage Rating:

CLM: 270 VAC/382 VDC

MLE: 310 VAC/438 VDC

Insertion Depth:

CLM:

Top Entry = (1.40 mm) .055" min.,

Bottom Entry =

(2.41 mm) .095" min.

(Add board thickness for

correct post OAL)

MLE:

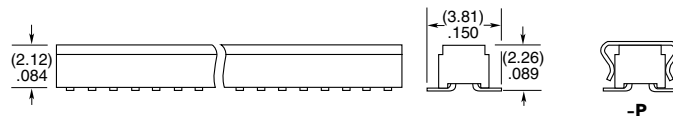
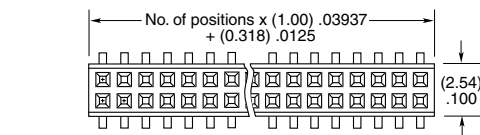
(1.63 mm) .064" to

(3.18 mm) .125" with

(0.38 mm) .015" wipe,

pass-through, or (2.44 mm) .096"

minimum for bottom entry



MLE

- 1

NO. PINS
PER ROW

- 01

PLATING
OPTION

- DV

OPTIONS

02 thru 50

PROCESSING

Lead-Free Solderable:

Yes

SMT Lead Coplanarity:

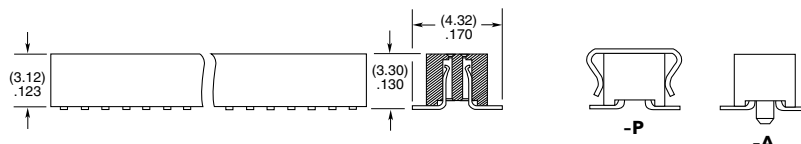
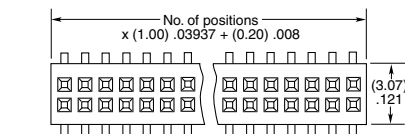
(0.10 mm) .004" max (02-25)

(0.15 mm) .006" max (26-50)*

*(.004" stencil solution

may be available; contact

ipg@samtec.com)



ALSO AVAILABLE

Contact Samtec

Alignment pin

Other Gold plating options



Note:

Some lengths, styles and options are non-standard, non-returnable.

F-224 (Rev 04SEP25)

samtec.com?CLM or samtec.com?MLE

Unless otherwise approved in writing by Samtec, all parts and components are designed and built according to Samtec's specifications which are subject to change without notice.